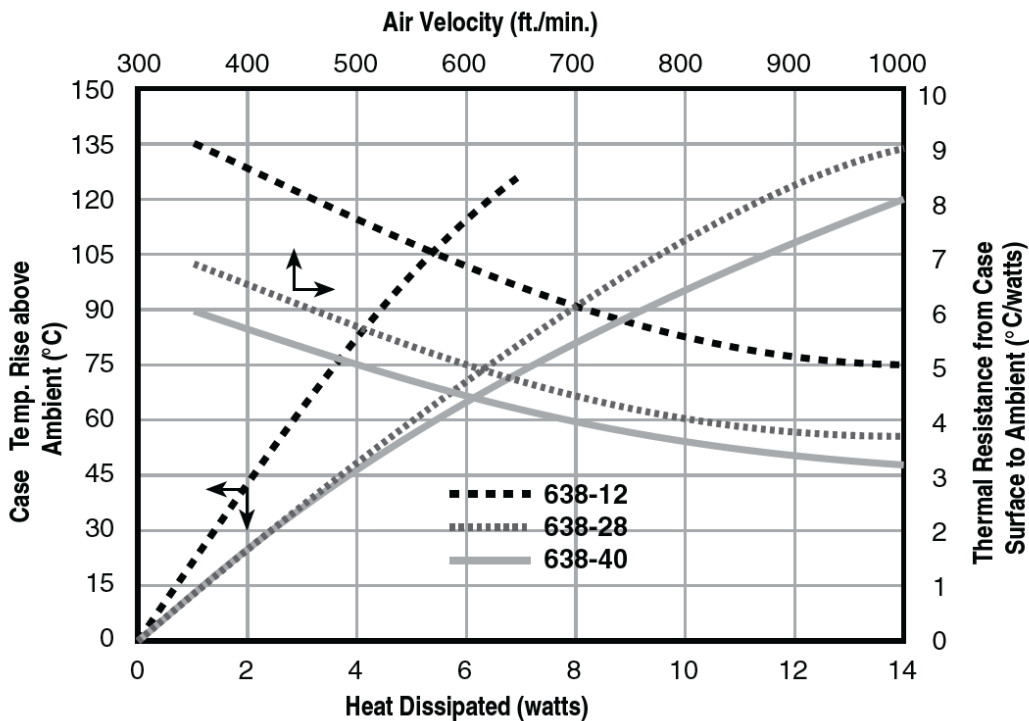
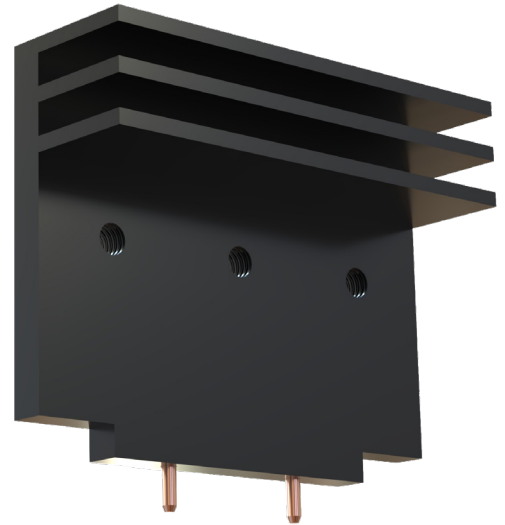


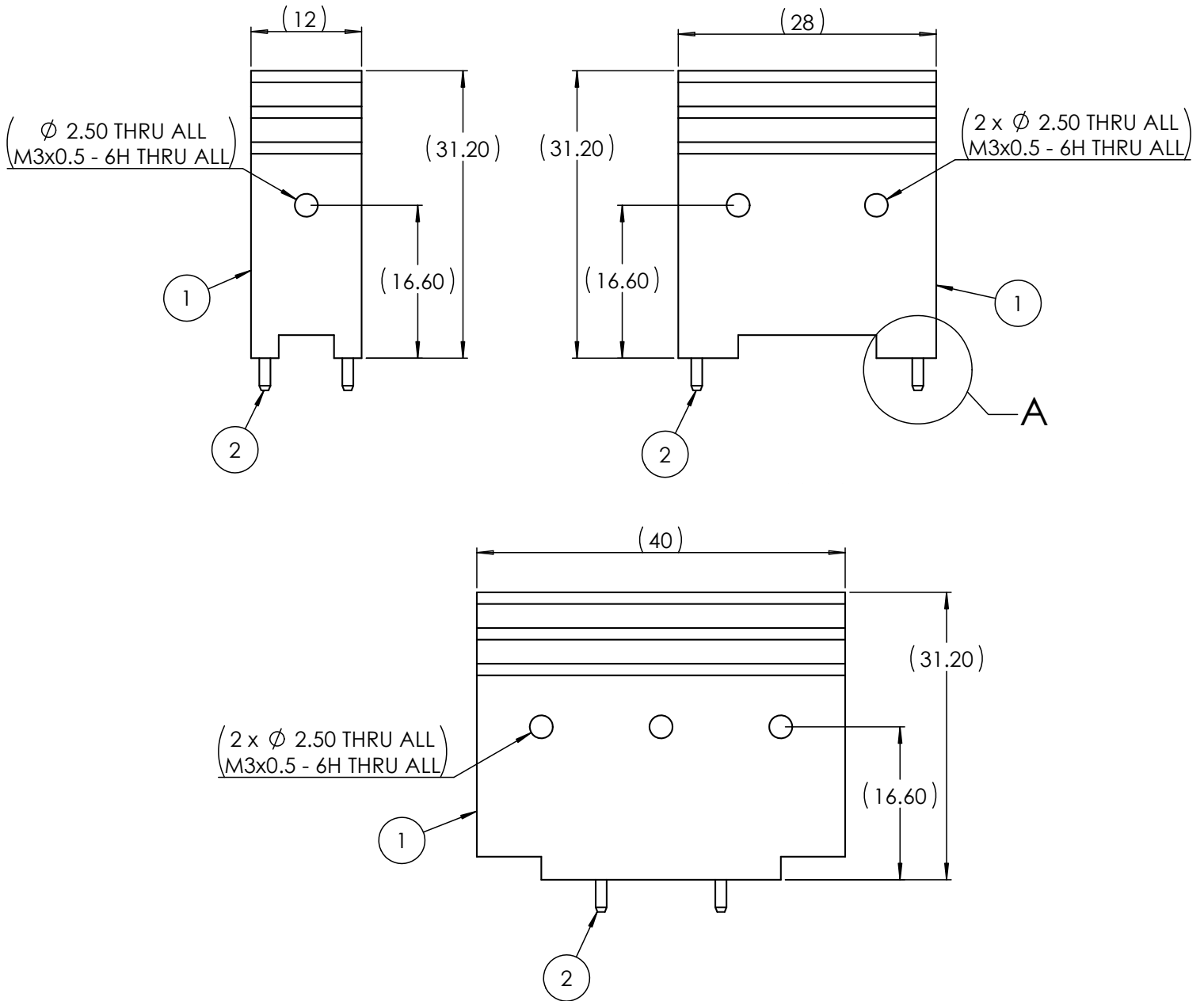
638 SERIES

Board-Mounted Heat Sinks

The Wakefield Thermal 638 Series of board-mounted heat sinks provides a compact, reliable thermal management solution for TO-220 power devices. With solderable feet designed for direct PCB mounting, these extruded aluminum heat sinks provide efficient heat dissipation while minimizing board space and simplifying assembly. Available in configurations for multiple devices, the 638 Series is well suited for power semiconductor applications requiring dependable thermal performance in a compact package.

Part #	Length (mm)	Width (mm)	Surface Area (mm ² / in ²)	Weight (oz / g)	Thermal Resistance (°C/W)
638-12	31.2	12	1,188 / 1.84	0.13 / 3.7	18.0
638-28	31.2	28	2,772 / 4.30	0.3 / 8.5	12.8
638-40	31.2	40	3,960 / 6.14	0.43 / 12.2	12.1





638-40

Sold through our Distribution Channels. For help finding the right Heat Sink for your project, contact us at:
Phone: (603) 635-2800 or communications@wakefieldthermal.com

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